




Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-05-12
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Laurent Tosi	Representative Title	MMS MD CHAMPION
Representative Phone *	(+33) 442 685 795	Representative Email *	laurent.tosi@st.com
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement	
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Legal Statement	
Supplier Acceptance *	true
Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM8S003F3P6	X5YA*767XXXY	A	9998	2014-03-24
	Amount	UoM	Unit type	ST ECOPACK Grade
	72,00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
-	6.5x4.4x1	20	L bend	
Comment	Package: YA TSSOP 20 BODY 4.4 PITCH 0.65			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-20th June 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	XSYA*767XXX					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	2,664	mg	supplier	die	Silicon (Si)	7440-21-3		2,576	mg	966967	35778
die (s)			mg	supplier	metallization	Aluminium (Al)	7429-90-5		0,007	mg	2628	97
die (s)			mg	supplier	metallization	Copper (Cu)	7440-50-8		0,031	mg	11637	431
die (s)			mg	supplier	metallization	Tantalum (Ta)	7440-25-7		0,002	mg	751	28
die (s)			mg	supplier	metallization	Titanium (Ti)	7440-32-6		0,004	mg	1502	56
die (s)			mg	supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0,006	mg	2252	83
die (s)			mg	supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0,038	mg	14264	528
LEADFRAME	Other inorganic materials	36,431	mg	supplier	ALLOY	Copper (Cu)	7440-50-8		34,408	mg	944470	477889
LEADFRAME			mg	supplier	ALLOY	Nickel (Ni)	7440-02-0		1,073	mg	29453	14903
LEADFRAME			mg	supplier	ALLOY	Silicon (Si)	7440-21-3		0,232	mg	6368	3222
LEADFRAME			mg	supplier	ALLOY	Magnesium (Mg)	7439-95-4		0,054	mg	1482	750
LEADFRAME			mg	supplier	COATING	Nickel (Ni)	7440-02-0		0,647	mg	17760	8986
LEADFRAME			mg	supplier	COATING	Palladium (Pd)	7440-05-3		0,014	mg	384	194
LEADFRAME			mg	supplier	COATING	Gold (Au)	7440-57-5		0,003	mg	82	42
DIE ATTACH	Other inorganic materials	0,848	mg	supplier	GLUE	Epoxy resin A	9003-36-5		0,059	mg	69575	819
DIE ATTACH			mg	supplier	GLUE	Epoxy resin B	68475-94-5		0,034	mg	40094	472
DIE ATTACH			mg	supplier	GLUE	Silver(Ag)	7440-22-4		0,653	mg	770047	9069
DIE ATTACH			mg	supplier	GLUE	Lactone	96-48-0		0,034	mg	40094	472
DIE ATTACH			mg	supplier	GLUE	Polyoxypropylenediamine	9046-10-0		0,034	mg	40094	472
DIE ATTACH			mg	supplier	GLUE	2,6-Diglycidyl phenyl allyl ether oligomer	Trade secret		0,034	mg	40094	472
BONDING WIRE	Other inorganic materials	0,270	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		0,267	mg	988889	3708
BONDING WIRE			mg	supplier	BONDING WIRE	Palladium (Pd)	7440-05-3		0,003	mg	11111	42
ENCAPSULATION	Other inorganic materials	31,516	mg	supplier	MOLDING COMPOUND	Epoxy Resin	Trade secret		2,772	mg	87955	38500
ENCAPSULATION			mg	supplier	MOLDING COMPOUND	Silica fused (SiO2)	60676-86-0		26,588	mg	843635	369278
ENCAPSULATION			mg	supplier	MOLDING COMPOUND	Phenol Resin	Trade secret		2,002	mg	63523	27806
ENCAPSULATION			mg	supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		0,154	mg	4886	2139
FINISHING	Other inorganic materials	0,271	mg	supplier	CONNECTION COATING	Nickel (Ni)	7440-02-0		0,264	mg	974170	3667
FINISHING			mg	supplier	CONNECTION COATING	Palladium (Pd)	7440-05-3		0,006	mg	22140	83
FINISHING			mg	supplier	CONNECTION COATING	Gold (Au)	7440-57-5		0,001	mg	3690	14